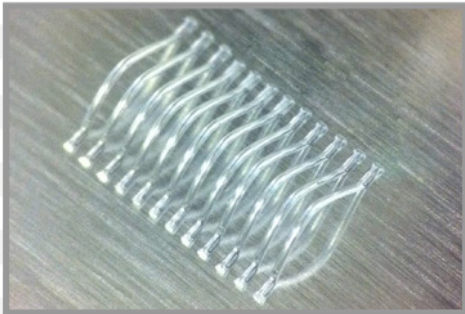




HB30 Heavy Wire Bonder

Motorized Z- & Y- Axis



- + 100 μ to 500 μ Aluminium Wire
- + 6,5" TFT Touch Screen
- + 100 Program storage capacities
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized Y travel for Step-Back loop control
- + 6:1 ratio X-Y manipulator
- + Loop Profile Programmable
- + Stitch bonding
- + Semi-auto, Step and Manual Bonding Mode

HB30 Heavy Wire Bonder

The HB30 is a **bench top size wire bonder**, ideal for laboratories, pilot and pre-production runs and small scale production lines. Easy operation with **TFT Touch Screen Operator System**. Direct access and simple adjustment to all bond parameters and programs.

Technical Spezifications

| | |
|-------------------|----------------|
| Ultrasonic system | PLL US System |
| Ultrasonic power | 20 Watt Output |
| Bond time | 0 - 10 sec. |
| Bond force | 50 - 1500 cN |

| | |
|-------------------------|------------------------|
| Aluminium wire diameter | 100 μ to 500 μ |
| Wire termination | Front Cut |
| Wire feed angle | 90° |
| Motorized Y travel | Stepback up to 17 mm |
| Motorized Z travel | 20 mm |
| Fine Table motion | 15 mm |
| Mouse ratio | 6:1 (Option 3:1) |

| | |
|-------------------------|--|
| Electrical Requirements | 100 - 240V +/-10% 50/60 Hz 10A max. |
| Physical Dimensions | 680 mm (27")W x 640 mm (25") D x 490 mm (19") H |
| Weight | Net 50 kg |
| Industry Standards | CE Standards |

Specifications are subject to change without prior notice

Accessories:



Spotlight tagetting system



Workstage



Manual Z



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